

MSE 170: Introduction to Materials Science and Engineering

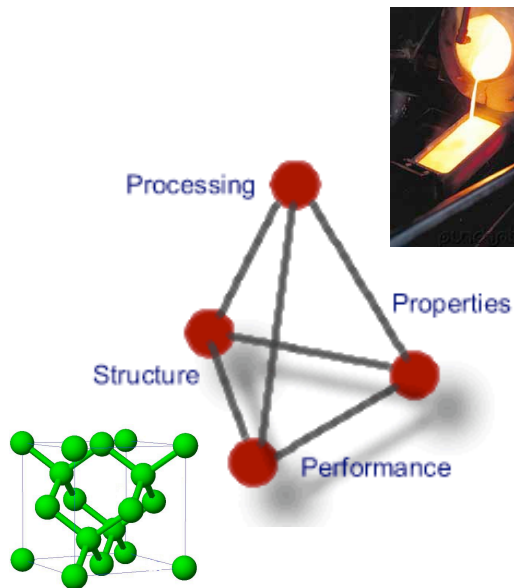
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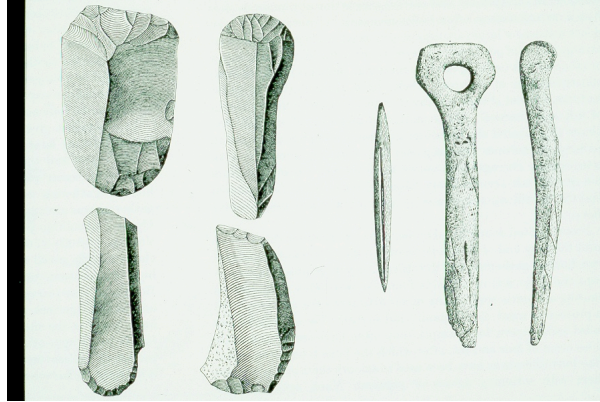
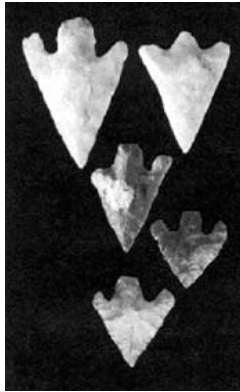
What is Materials Science and Engineering?



An interdisciplinary field that addresses the fundamental relationships between the **Processing, Structure and Properties** of materials and develops them for the desired technological application (**Performance**).

Materials through the ages

Stone Age (beginning of life – 3000 BC)



Feature: Using naturally occurring materials with only changes in shape

Materials through the ages

Bronze Age (3000 BC – 1200 BC)

Copper and Tin alloy



Ability to modify materials by refining (using heat), chemical modifications (alloying) and mechanical deformation (cold working)

Imperfection (Ch. 4)
Diffusion (Ch. 5)
Phase diagram (Ch. 9)
Metal Processing (Ch. 11)

Materials through the ages



Iron Age (1200 BC – Present)

Casting and alloying wasn't perfected until 16th century

Mastery of Steel (Iron alloy) technology enables Industrial Revolution in the 18th and 19th century

Ability to heat treat at high temperature, control microstructure at different length scale and ability to design specific microstructures for specific properties

Phase transformation (Ch. 10)

Materials through the ages

Plastic Age (1940 - Present)

Discovery of polymers, and the ability to synthesize and process polymers.



Materials through the ages

Silicon Age (1950 - Present)

Commercialization of silicon technology (integrated circuits, electronic devices, etc...) leads to the information age, which gives boost to human productivity

Electronic Prop. (Ch.18)
Thermal Prop. (Ch.19)
Magnetic Prop. (Ch.20)
Optical Prop. (Ch.21)

Ability to control alloying accurately,
ability to make thin films



Future

1. Nanotechnology

- Synthesis and characterizations of nanomaterials and nanostructure

2. Biotechnology

- biomimetics and biomaterials

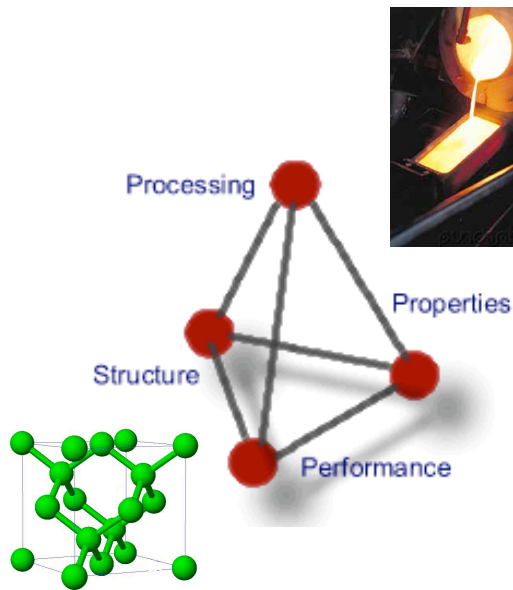
3. Energy/Environmental

- Next generation energy conversion

4. Information Technology

- Materials informatics

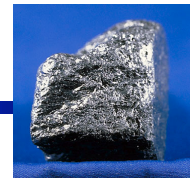
What is Materials Science and Engineering?



An interdisciplinary field that addresses the fundamental relationships between the **Processing, Structure and Properties** of materials and develops them for the desired technological application (**Performance**).

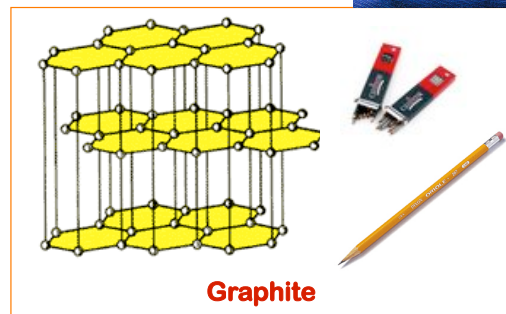


Two Forms of Carbon



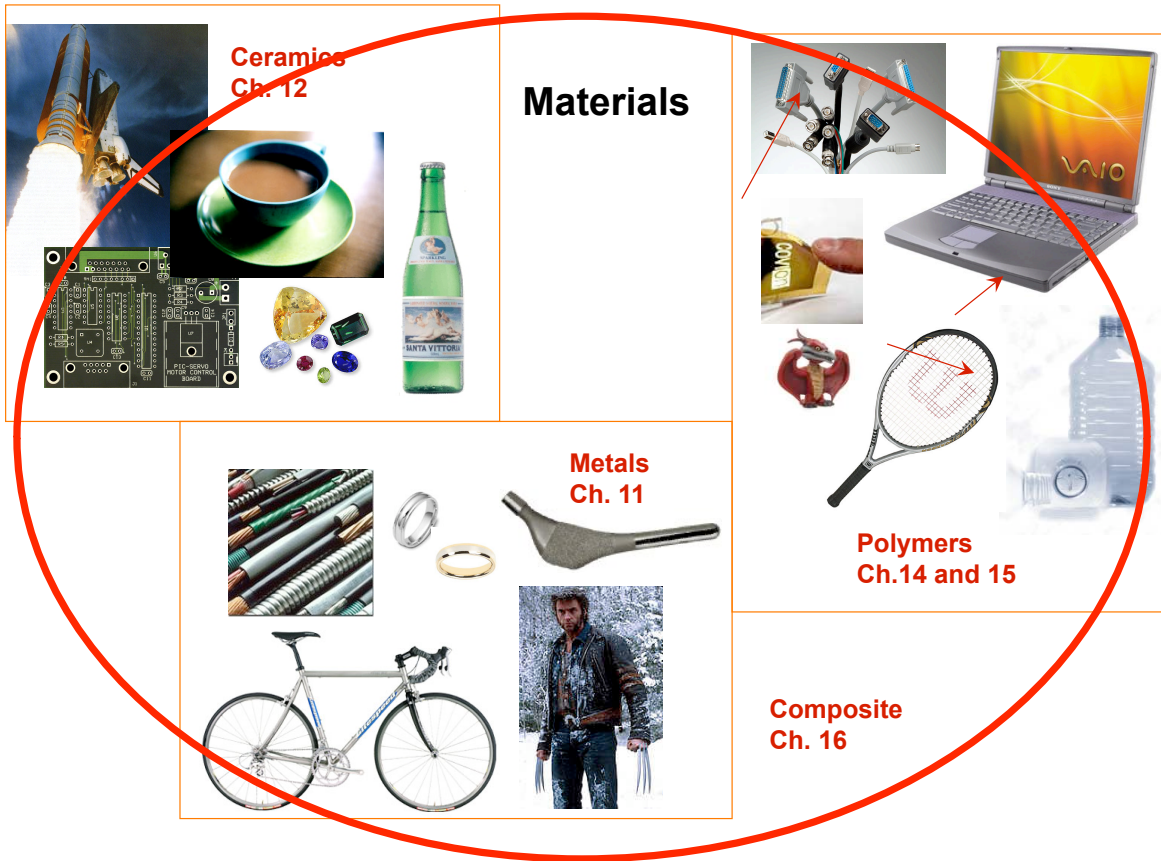
- A structure of carbon only produced at high temperature and pressure.
- The hardest known material.

VS.

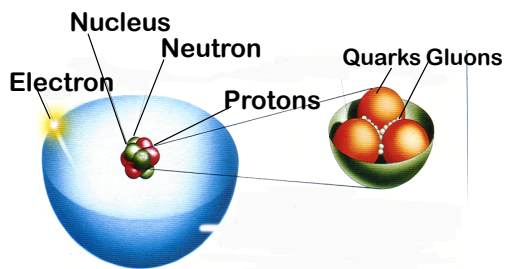


- A structure of carbon that is in equilibrium (it is stable and will not change form over time).
- It is soft.

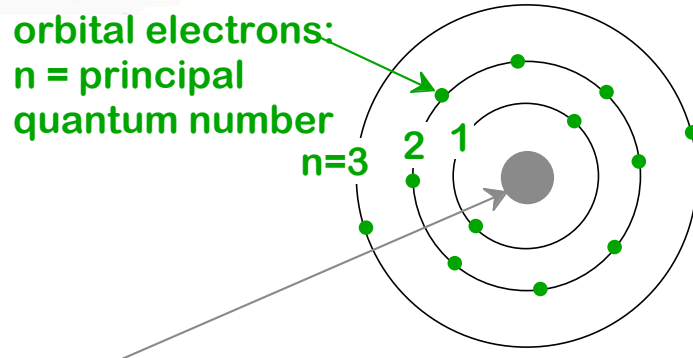
Atomic structure and interatomic bonding (Ch.2)
Crystallography (Ch. 3), Imperfection (Ch. 4)



Atomic structure



BOHR ATOM



Nucleus: $Z =$

Atomic mass $A \approx$

$N =$

Electronic structure

Valence electrons determine all of the following properties:

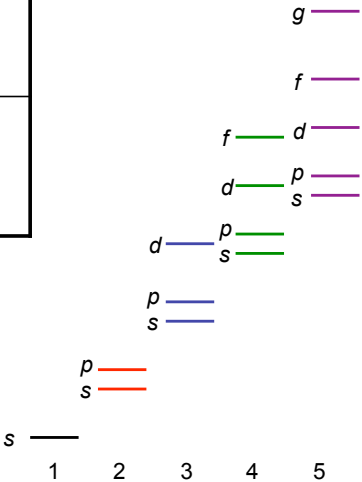
- Electrons have wavelike and particulate properties.
- This means that electrons are in **orbitals** defined by a probability.
 - Each orbital at discrete energy level determined by **quantum numbers**.

Quantum #

Designation

Electronic structure

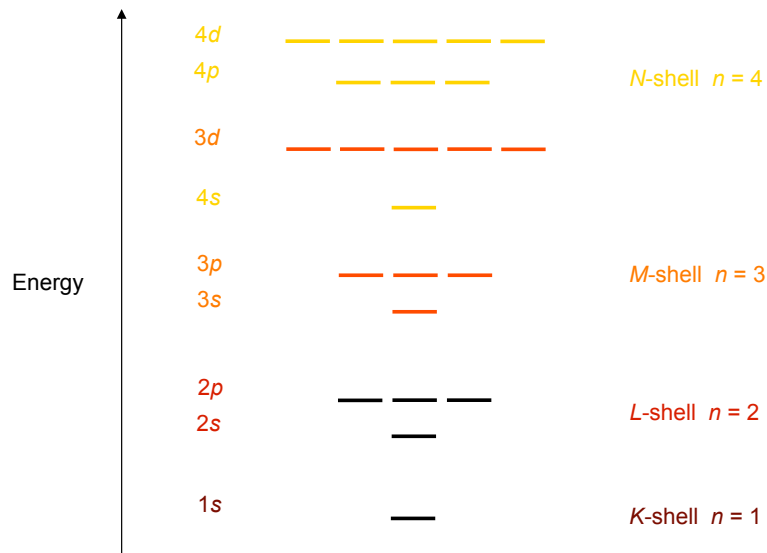
Principal quantum no.	Shell designation	Subshells	No. of states	Number of electrons	
				Per subshell	Per shell
1	K	s	1	2	2
2	L	s	1	2	8
		p	3	6	
3	M	s	1	2	18
		p	3	6	
		d	5	10	
4	N	s	1	2	32
		p	3	6	
		d	5	10	
		f	7	14	



Electron energy states

Electrons...

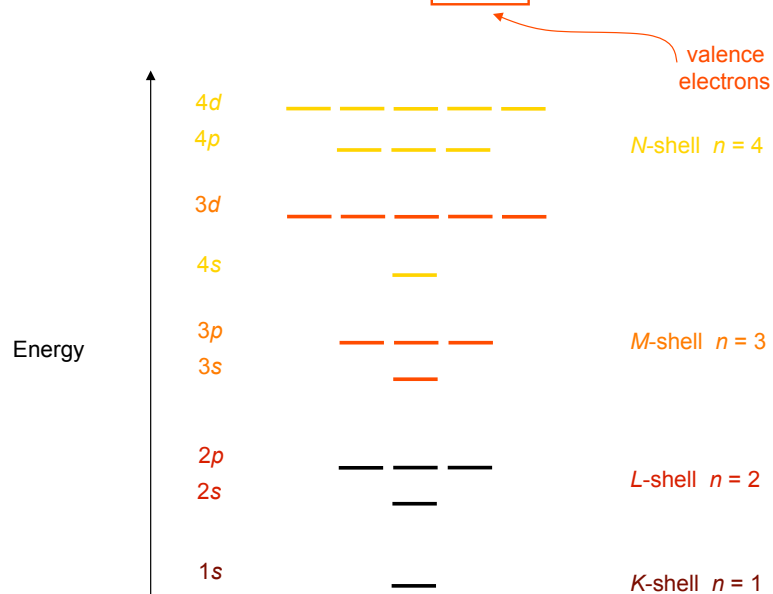
- have discrete **energy states**
- tend to occupy lowest available energy state.



Adapted from Fig. 2.4,
Callister 7e.

Electronic configuration

ex: Fe - atomic # = $1s^2 2s^2 2p^6 3s^2 3p^6 3d^6 4s^2$



Adapted from Fig. 2.4,
Callister 7e.

Electronegativity

- Ranges from 0.7 to 4.0,
- Large values: tendency to acquire electrons.

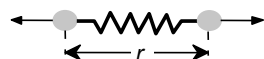
IA																		0
H																		He
2.1																		-
Li	Be																	Ne
1.0	1.5																	-
Na	Mg																	Ar
0.9	1.2																	-
		IIIB	IVB	VB	VIB	VII B	VIII				IB	IIB						-
K	Ca	Sc	Ti	V	Cr	Mn	Fe	Co	Ni	Cu	Zn	Ga	Ge	As	Se	Br	Kr	
0.8	1.0	1.3	1.5	1.6	1.6	1.5	1.8	1.8	1.8	1.9	1.6	1.6	1.8	2.0	2.4	2.8	-	
Rb	Sr	Y	Zr	Nb	Mo	Tc	Ru	Rh	Pd	Ag	Cd	In	Sn	Sb	Te	I	Xe	
0.8	1.0	1.2	1.4	1.6	1.8	1.9	2.2	2.2	2.2	1.9	1.7	1.7	1.8	1.9	2.1	2.5	-	
Cs	Ba	La-Lu	Hf	Ta	W	Re	Os	Ir	Pt	Au	Hg	Tl	Pb	Bi	Po	At	Rn	
0.7	0.9	1.1-1.2	1.3	1.5	1.7	1.9	2.2	2.2	2.2	2.4	1.9	1.8	1.8	1.9	2.0	2.2	-	
Fr	Ra	Ac-No																
0.7	0.9	1.1-1.7																

Smaller electronegativity

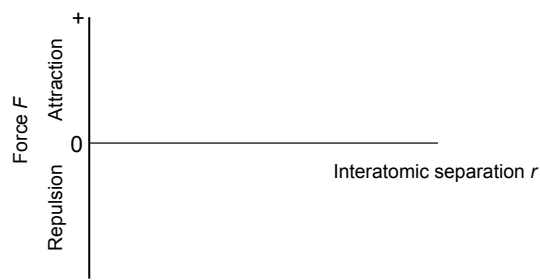
Larger electronegativity

Adapted from Fig. 2.7, *Callister 7e*. (Fig. 2.7 is adapted from Linus Pauling, *The Nature of the Chemical Bond*, 3rd edition, Copyright 1939 and 1940, 3rd edition. Copyright 1960 by Cornell University.

Bonding forces and energies

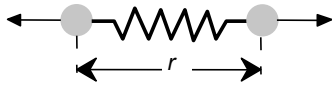


- Attractive force, F_A
- Repulsive force, F_R

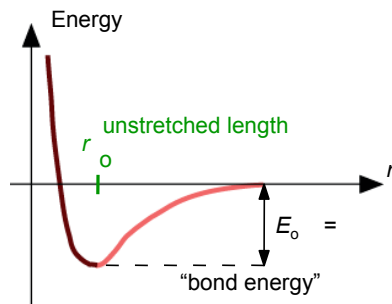


Properties from bonding

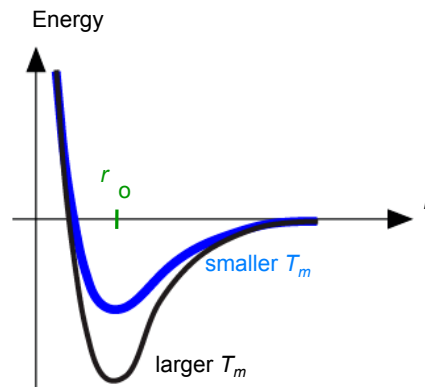
- Bond length, r



- Bond energy, E_0



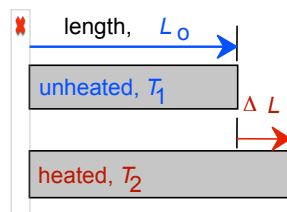
- Melting Temperature, T_m



T_m is larger if E_0 is larger.

Properties from bonding: thermal expansion coefficient

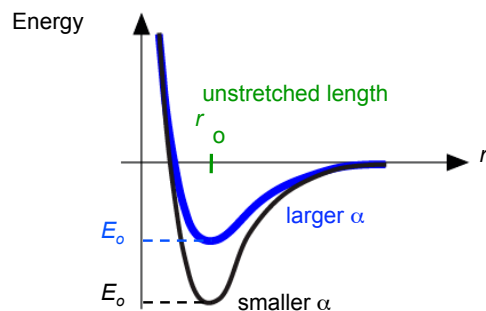
- Coefficient of thermal expansion, α



coeff. thermal expansion

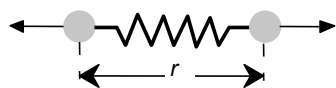
$$\frac{\Delta L}{L_0} = \alpha (T_2 - T_1)$$

- $\alpha \sim$ symmetry at r_0

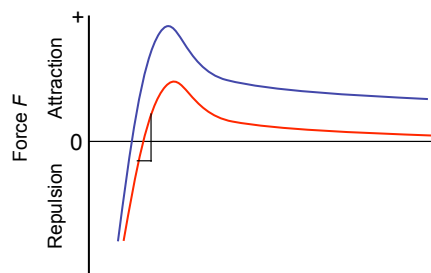


α is larger if E_0 is smaller.

Properties from bonding: modulus E



$$F = kx$$



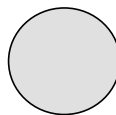
Types of bonding: ionic

- Occurs between + and - ions.
- Requires [electron transfer](#).
- Large difference in electronegativity required.
- Example: NaCl

Na (metal)
unstable



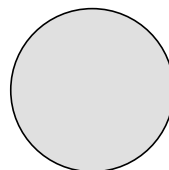
Cl (nonmetal)
unstable



Na (cation)
stable

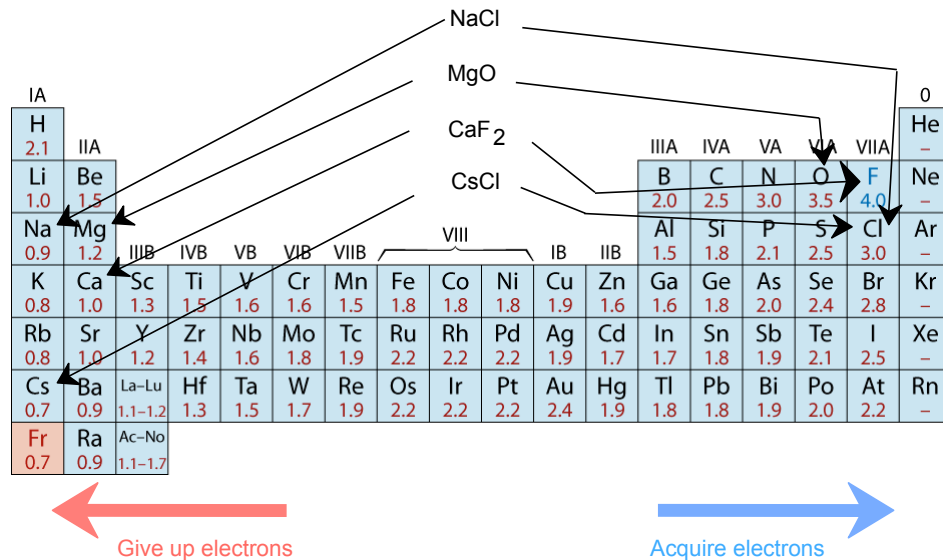


Cl (anion)
stable



Examples of ionic bonding

- Predominant bonding in **Ceramics**



Adapted from Fig. 2.7, *Callister 7e*. (Fig. 2.7 is adapted from Linus Pauling, *The Nature of the Chemical Bond*, 3rd edition, Copyright 1939 and 1940, 3rd edition. Copyright 1960 by Cornell University.

Covalent bonding

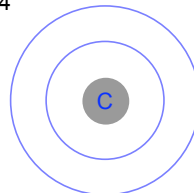
- similar **electronegativity** \therefore share electrons
- bonds determined by valence – s & p orbitals dominate bonding
- Example: CH₄

C: has 4 valence e⁻,
needs 4 more

H: has 1 valence e⁻,
needs 1 more

Electronegativities
are comparable.

CH₄



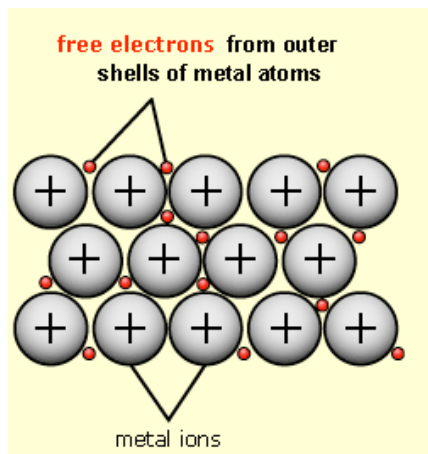
• shared electrons
from carbon atom

• shared electrons
from hydrogen
atoms

Adapted from Fig. 2.10, *Callister 7e*.

Metallic bonding

- Ions in a sea of electrons
- Attraction between free electrons and metal ions



Ionic-covalent mixed bonding

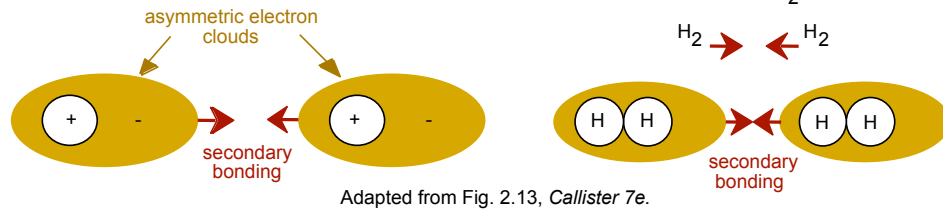
$$\% \text{ ionic character} = \left(1 - e^{-\frac{(X_A - X_B)^2}{4}} \right) \times (100 \%)$$

where X_A & X_B are Pauling electronegativities

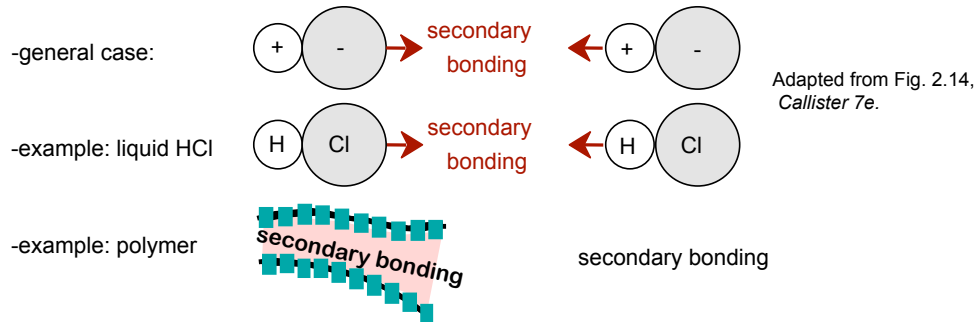
Secondary bonding

Arises from interaction between **dipoles**

- Fluctuating **dipoles**



- Permanent **dipoles**-molecule induced



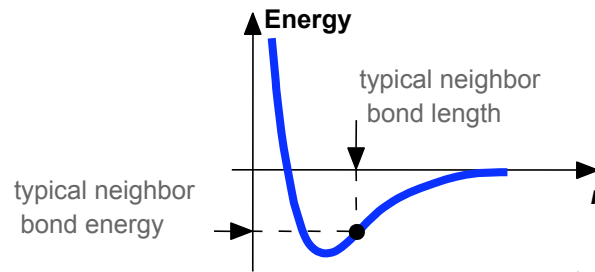
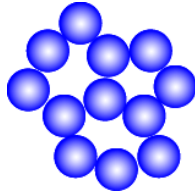
Summary

Type	Bond Energy	Comments
Ionic	Large!	Non-directional (ceramics)
Covalent	Variable Diamond (large) Bismuth (small)	Directional (semiconductors , ceramics , polymer chains)
Metallic	Variable Tungsten (large) Mercury (small)	Non-directional (metals)
Secondary	Smallest	Directional Interchain (polymer) Intermolecular

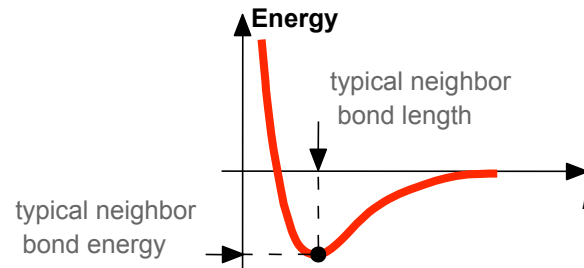
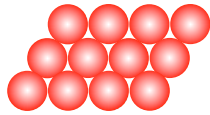
Ceramics (Ionic & covalent bonding)	Large bond energy Large T_m and E , small α
Metals (Metallic bonding)	Variable bond energy Moderate T_m , E , and α
Polymers (Covalent & secondary)	Directional properties, Secondary bonding dominates Small T_m and E , large α

Energy and packing

- Non dense, *random* packing



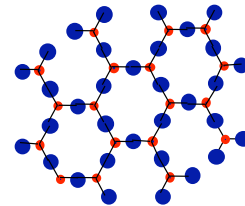
- Dense, *ordered* packing



Dense, ordered packed structures tend to have lower energies.

Materials and packing

Crystalline materials...

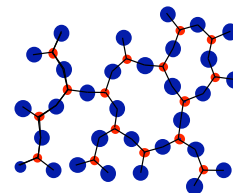


crystalline SiO₂

Adapted from Fig. 3.22(a),
Callister 7e.

● Si ● Oxygen

Noncrystalline materials...



noncrystalline SiO₂

Adapted from Fig. 3.22(b),
Callister 7e.

Crystals

Unit cell:

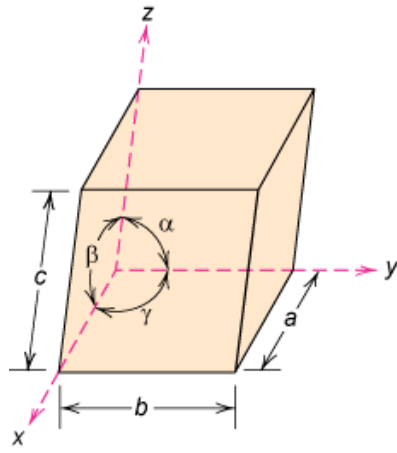
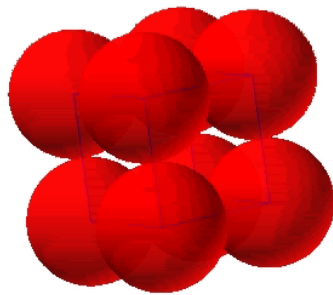


Fig. 3.4, Callister 7e.

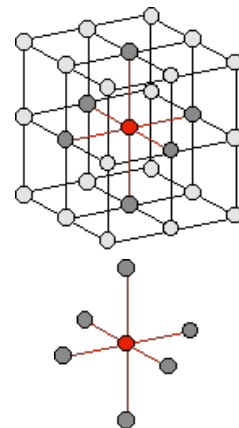
a , b , and c are the lattice constants

Simple cubic structure (SC)

- Rare due to low packing density (only Po has this structure)
- Close-packed directions are cube edges.



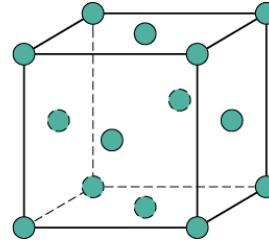
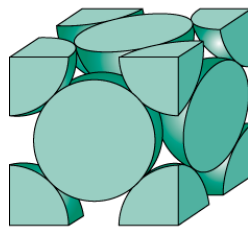
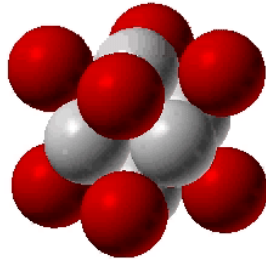
(Courtesy P.M. Anderson)



Face centered cubic structure (FCC)

- Atoms touch each other along face diagonals.
 - Note: All atoms are identical; the face-centered atoms are shaded differently only for ease of viewing.

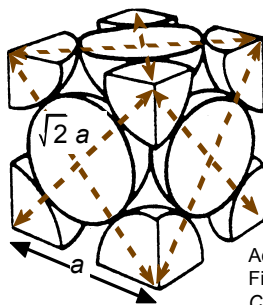
ex: Al, Cu, Au, Pb, Ni, Pt, Ag



Adapted from Fig. 3.1, *Callister 7e*.

(Courtesy P.M. Anderson)

Atomic packing factor (APF): FCC



Adapted from
Fig. 3.1(a),
Callister 7e.

close-packed directions

contains $6 \times \frac{1}{2} + 8 \times \frac{1}{8} =$

4 atoms/unit cell

Theoretical density, ρ

$$\text{Density} = \rho = \frac{\text{Mass of atoms in unit cell}}{\text{Total volume of unit cell}}$$

$$\rho = \frac{nA}{V_C N_A}$$

where

n = number of atoms/unit cell

A = atomic weight

V_C = Volume of unit cell = a^3 for cubic

N_A = Avogadro's number

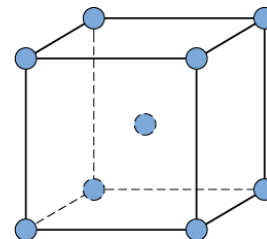
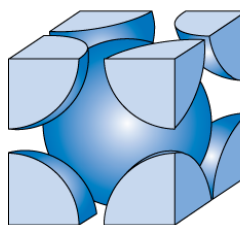
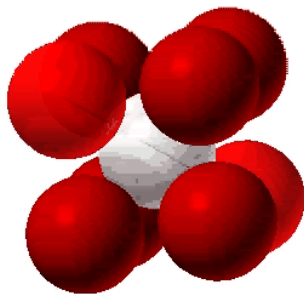
= 6.023×10^{23} atoms/mol

Body centered cubic structure (BCC)

- Atoms touch each other along cube diagonals.

--Note: All atoms are identical; the center atom is shaded differently only for ease of viewing.

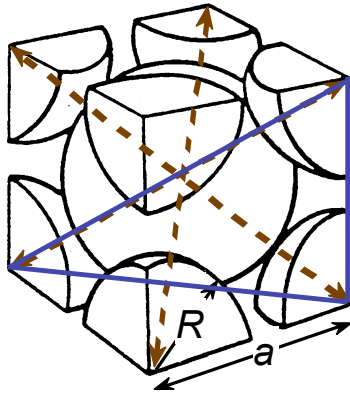
ex: Cr, W, Fe (α), Tantalum, Molybdenum



Adapted from Fig. 3.2,
Callister 7e.

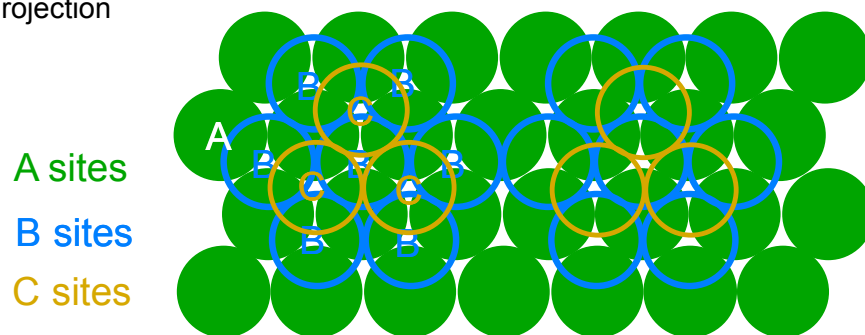
(Courtesy P.M. Anderson)

Atomic packing factor (APF): BCC

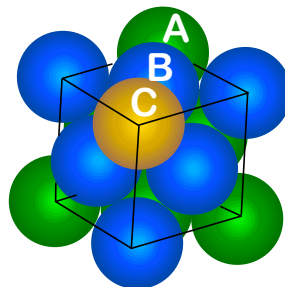


FCC stacking sequence

- ABCABC... Stacking Sequence
- 2D Projection



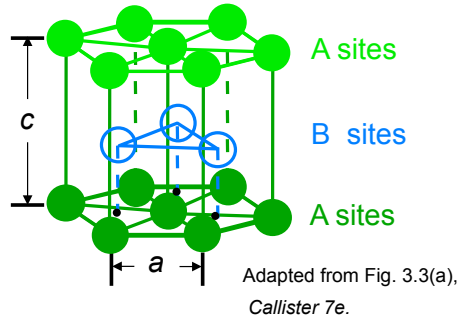
- FCC Unit Cell



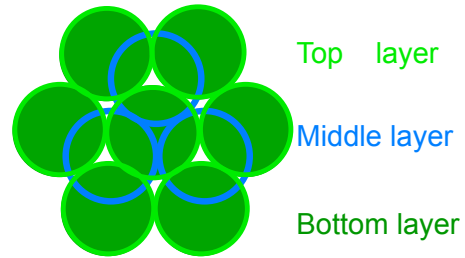
Hexagonal close-packed structure (hcp)

- ABAB... Stacking Sequence

- 3D Projection



- 2D Projection



6 atoms/unit cell

ex: Cd, Mg, Ti, Zn